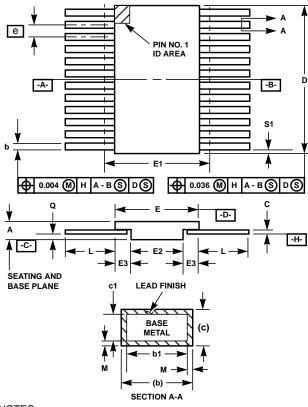
Ceramic Metal Seal Flatpack Packages (Flatpack)



NOTES:

- Index area: A notch or a pin one identification mark shall be located adjacent to pin one and shall be located within the shaded area shown. The manufacturer's identification shall not be used as a pin one identification mark. Alternately, a tab (dimension k) may be used to identify pin one.
- 2. If a pin one identification mark is used in addition to a tab, the limits of dimension k do not apply.
- 3. This dimension allows for off-center lid, meniscus, and glass overrun.
- 4. Dimensions b1 and c1 apply to lead base metal only. Dimension M applies to lead plating and finish thickness. The maximum limits of lead dimensions b and c or M shall be measured at the centroid of the finished lead surfaces, when solder dip or tin plate lead finish is applied.
- 5. N is the maximum number of terminal positions.
- 6. Measure dimension S1 at all four corners.
- 7. For bottom-brazed lead packages, no organic or polymeric materials shall be molded to the bottom of the package to cover the leads.
- Dimension Q shall be measured at the point of exit (beyond the meniscus) of the lead from the body. Dimension Q minimum shall be reduced by 0.0015 inch (0.038mm) maximum when solder dip lead finish is applied.

48

- 9. Dimensioning and tolerancing per ANSI Y14.5M 1982.
- 10. Controlling dimension: INCH.

K20.A MIL-STD-1835 CDFP4-F20 (F-9A, CONFIGURATION	B)
20 LEAD CERAMIC METAL SEAL FLATPACK PACKAGE	

	INCHES		MILLIN		
SYMBOL	MIN	MAX	MIN	MAX	NOTES
А	0.045	0.115	1.14	2.92	-
b	0.015	0.022	0.38	0.56	-
b1	0.015	0.019	0.38	0.48	-
С	0.004	0.009	0.10	0.23	-
c1	0.004	0.006	0.10	0.15	-
D	-	0.540	-	13.72	3
E	0.245	0.300	6.22	7.62	-
E1	-	0.330	-	8.38	3
E2	0.130	-	3.30	-	-
E3	0.030	-	0.76	-	7
е	0.050 BSC		1.27	BSC	-
k	0.008	0.015	0.20	0.38	2
L	0.250	0.370	6.35	9.40	-
Q	0.026	0.045	0.66	1.14	8
S1	0.00	-	0.00	-	6
М	-	0.0015	-	0.04	-
N	20		2	20	-

Rev. 0 5/18/94